

In the Claims:

1. (Currently amended) A light emitting diode arrangement, comprising a flexible circuit board and at least one high power light emitting diode ~~(34), the high power light emitting diode (34) being~~ mounted onto a said flexible printed circuit board ~~(10)~~.

2. (Currently amended) The light emitting diode arrangement as claimed in claim 1, in which the high power light emitting diode ~~(34)~~ has a power consumption of at least 300 mW.

3. (Currently amended) The light emitting diode arrangement as claimed in claim 1, ~~claims 1 and 2~~, in which the high power light emitting diode ~~(34)~~ is soldered onto the flexible ~~printed~~ circuit board ~~(10)~~.

4. (Currently amended) The light emitting diode arrangement as claimed in claim 3, in which the flexible ~~printed~~ circuit board ~~(10)~~ contains at least one flexible carrier layer ~~(33)~~.

5. (Currently amended) The light emitting diode arrangement as claimed in claim 4, in which the flexible carrier layer ~~(33)~~ contains at least one of the following materials: polyimide, polyethylene naphthalate, polyester, FR4.

6. (Currently amended) The light emitting diode arrangement as claimed in claim 1 ~~claims 1 to 5~~,

in which the flexible ~~printed~~ circuit board ~~(34)~~ contains a thermally conductive layer ~~(21)~~ which is in thermal contact with the high power light emitting diode ~~(34)~~.

7. (Currently amended) The light emitting diode arrangement as claimed in claim 6, in which the thermally conductive layer ~~(21)~~ contains a metal.

8. (Currently amended) The light emitting diode arrangement as claimed in claim 6 ~~claims 6 and 7~~, in which the thermally conductive layer ~~(21)~~ contains copper.

9. (Currently amended) The light emitting diode arrangement as claimed in claim 6 ~~claims 6 to 8~~, in which the high power light emitting diode ~~(34)~~ is soldered onto the thermally conductive layer ~~(21)~~.

10. (Currently amended) The light emitting diode arrangement as claimed in claim 1, ~~one of claims 1 to 9~~, in which the flexible ~~printed~~ circuit board ~~(10)~~ contains electrical conductor tracks ~~(22),(23)~~, the thermally conductive layer ~~(21)~~ and the electrical conductor tracks ~~(22),(23)~~ being situated in one plane of the flexible ~~printed~~ circuit board ~~(10)~~.

11. (Currently amended) The light emitting diode arrangement as claimed in claim 10, in which the thermally conductive layer ~~(21)~~ and the electrical conductor tracks ~~(22),(23)~~ contain the same metal.

12. (Currently amended) The light emitting diode arrangement as claimed in claim 1, ~~claims 1 to 11~~, in which an insulating layer ~~(12)~~ is applied to one of the surfaces of the flexible ~~printed~~ circuit board ~~(10)~~.

13. (Currently amended) The light emitting diode arrangement as claimed in claim 12, in which the insulating layer ~~(12)~~ has cutouts for making electrical and thermal contact with the high power light emitting diode ~~(34)~~.

14. (Currently amended) The light emitting diode arrangement as claimed in claim 12, ~~claims 12 and 13~~, in which the insulating layer ~~(12)~~ contains a soldering resist.

15. (Currently amended) The light emitting diode arrangement as claimed in claim 1, ~~claims 1 to 14~~, in which that side of the flexible ~~printed~~ circuit board ~~(10)~~ which is remote from the high power light emitting diodes ~~(34)~~ has an adhesive-containing layer ~~(32)~~.

16. (Currently amended) The light emitting diode arrangement as claimed in claim 15, in which the adhesive-containing layer ~~(32)~~ is formed by a double sided adhesive tape.

17. (Currently amended) The light emitting diode arrangement as claimed in claim 15 ~~claims 15 or 16~~, in which the adhesive-containing layer ~~(32)~~ is heat-resistant up to temperatures of 250°C.

18. (Currently amended) The light emitting diode arrangement as claimed in claim 15, ~~claims 15 to 17~~, in which the adhesive-containing layer ~~(32)~~ has a thickness of at most 60 μm .

19. (Currently amended) The light emitting diode arrangement as claimed in claim 15, ~~claims 15 to 18~~, in which the adhesive-containing layer ~~(32)~~ is covered with a protective film ~~(31)~~.

20. (Currently amended) The light emitting diode arrangement as claimed in claim 19, in which the protective film ~~(31)~~ contains a plastic.

21. (Currently amended) The light emitting diode arrangement as claimed in claim 1, ~~one of the preceding claims~~, in which a multiplicity of high power light emitting diodes ~~(34)~~ are provided, which diodes are connected in series.

22. (Currently amended) The light emitting diode arrangement as claimed in claim 21, in which a pair of contact areas ~~(15)~~ is provided for each high power light emitting diode ~~(34)~~.

23. (Currently amended) The light emitting diode arrangement as claimed in claim 22, which has sections, ~~(11)~~ each section having a high power light emitting diode ~~(34)~~ and the associated pair of contact areas ~~(15)~~.

24. (Currently amended) The light emitting diode arrangement as claimed in claim 23, in which the sections ~~(11)~~ are arranged as repeating structures.

25. (Currently amended) The light emitting diode arrangement as claimed in claim 24, in which the sections ~~(11)~~ are arranged in a series.

26. (Currently amended) An illumination device, having a light emitting diode arrangement as claimed in claim 1, ~~one of the preceding claims, and~~ a heat sink ~~being predefined~~, on which the light emitting diode arrangement is applied.

27. (Original) The illumination device as claimed in claim 26, in which the light emitting diode arrangement is adhesively bonded onto the heat sink.

28. (Currently amended) The illumination device as claimed in claim 26 ~~or 27~~, in which the heat sink contains a metal.

29. (Currently amended) The illumination device as claimed in claim 26 ~~to 28~~, in which the heat sink is part of a ~~luminaire~~ lamp housing.

30. (Currently amended) The illumination device as claimed in claim 29, in which the ~~luminaire~~ lamp housing is the housing for one of the following ~~luminaries~~ lamps: automobile interior illumination, automobile rear illumination, brake light, flashing indicator.

31. (Currently amended) A method for producing a light emitting diode arrangement, wherein firstly an adhesive-containing layer ~~(32)-being~~ is applied to a ~~the~~ flexible ~~printed~~ circuit board ~~(10)~~ and then light emitting diodes ~~(34)-being~~ are soldered onto that side of the flexible ~~printed~~ circuit board ~~(10)~~ which is remote from the adhesive-containing layer ~~(32)~~.